

PVD SERVICES

Thin Film Metals – Aluminum, Titanium, Titanium Nitride, Chrome

Features

- Low Particle Processing utilizing a Vertical Pallet Loading System
- All Multi Layer Stacks Are Processed without Breaking Vacuum to Insure Optimum Adhesion Between Film Layers
- Uniformity $<\pm 5\%$

Films

Ti	Less Than 200A $\pm 20\%$ 200A to 1500A $\pm 10\%$ 1500A to 3000A $\pm 5\%$
TiN	Less Than 250A $\pm 20\%$ 250A to 1500A $\pm 10\%$ 1500A to 3000A $\pm 5\%$
Al 99.999%	500 to 1000A $\pm 10\%$ 1000A to 5000A $\pm 5\%$ 5000A to 10000A 0.5um to 1.0 μm $\pm 5\%$ 10000A to 20000A 1.0um to 2.0 μm $\pm 5\%$
Cr	Less Than 250A $\pm 20\%$ 250A to 1500A $\pm 10\%$ 1500A to 3000A $\pm 5\%$

Wafer Size

mm	Inches
100	4
125	5
150	6
200	8
300	12

Tool

MRC 603 Sputtering System

Notes

- Inspection Criteria of Film: 100% Visual Inspection for uniform, defect-free films
- No Clamp marks: All customer provided substrates must be clean and ready to sputter, unless cleaning is quoted by Noel Technologies.
- Film Thickness Measurement: Tencor Alpha Step 100
- Certification of Conformance will be supplied for each lot.